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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of  
Yoshihisa FURUTA, et al.

Docket No: Q62228

Appln. No.: 09/719,422

Group Art Unit: 1733

Confirmation No.: 7788

Examiner: Barbara J. MUSSER

*10B/KW  
2/21/03*

Filed: December 12, 2000

For: METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND  
PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME AND  
THE LIKE

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents  
Washington, D.C. 20231

Sir:

This is responsive to the Office Action dated November 12, 2002. Please amend the  
above-identified application as follows:

IN THE CLAIMS:

Please enter the following amended claims:

2. (Amended) A resin encapsulating method for a semiconductor chip comprising  
adhering a pressure-sensitive adhesive tape to a tape carrier film, bonding a semiconductor chip  
to the tape carrier film having the pressure-sensitive adhesive tape adhered thereto, encapsulating  
the semiconductor chip with a resin and a mold, and stripping the pressure-sensitive adhesive  
tape, wherein the pressure-sensitive adhesive tape has a thermal shrinkage of 3% or less on resin  
encapsulating.

*B!*